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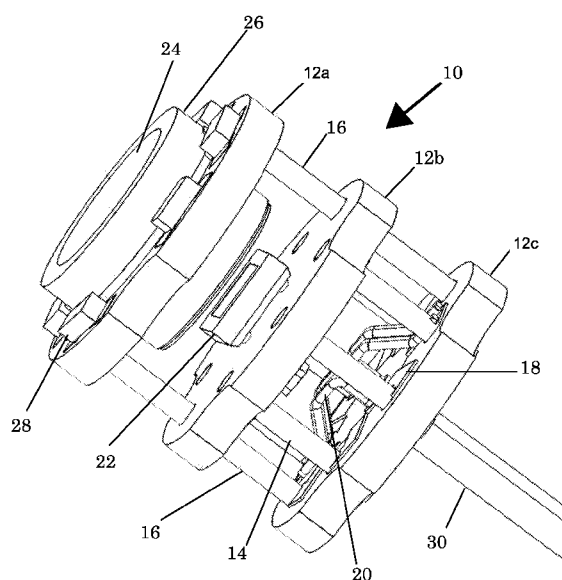


Fig. 1

(57) **Abstract:** A video camera head is comprised of at least two rigid printed circuit boards (PCBS) arranged in parallel planes. The at least two PCBs are mechanically supported one above the other by pins made of an electricity conducting material that conduct electrical power from the bottom PCB to electronic components or illumination means mounted on the other PCBs and signals from a solid state sensor chip mounted on one of the other PCBs of the at least two PCBs to the bottom PCB. Several embodiments of the video camera head are described.

CAMERA HEAD

Field of the Invention

The invention is from the field of video cameras. Specifically the invention relates to small diameter camera heads for use in such applications as medical endoscopes and laparoscopes and industrial borescopes.

Background of the Invention

Ever since their first use it has been the goal of designers of medical endoscopes and laparoscopes and industrial borescopes to reduce the diameter of the instruments in order to allow access through smaller and smaller diameter orifices.

Methods of accomplishing reductions in the diameter are discussed for example in WO2011/033513 in which the Applicant of the present invention describes camera heads having an outer diameter of 1.4mm or less.

Two of the obstacles to even further reduction in diameter are the flexible PCB substrates on which the sensor and other components of the camera head are generally mounted and the internal wiring that electrically connects the various electronic components. A third obstacle connected with small diameter camera heads such as those described in WO2011/033513 is the difficulty of assembly, in particular connecting the internal wiring, which is not suitable to mass production manufacturing.

A fourth obstacle is related to the need of integrated illumination in the aforementioned devices and the difficulty of transferring adequate amounts of current while maintaining the minimal dimensions of the camera-illumination assembly.

It is therefore a purpose of the present invention to provide a camera head which addresses the above mentioned obstacles.

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Further purposes and advantages of this invention will appear as the description proceeds.

Summary of the Invention

In a first aspect the invention is a video camera head comprised of at least two rigid printed circuit boards (PCBs) arranged in parallel planes. The PCBs are mechanically supported one above the other by pins made of an electricity conducting material. The pins conduct electrical power from the bottom PCB to electronic components and/or illumination means mounted on the other PCBs of the at least two PCBs and signals from a sensor chip mounted on one of the other PCBs of the at least two PCBs to the bottom PCB.

In embodiments of the video camera head of the invention the illumination means comprise at least one LED, e.g. a ring array of LEDs.

Embodiments of the video camera head of the invention comprise an objective optical system.

In embodiments of the video camera head of the invention comprised of three PCBs components for receiving signals from a solid state sensor and outputting a video signal are mounted on the bottom PCB, a solid state sensor chip is mounted on the middle PCB, and an objective optical system and illumination means are mounted on the top PCB. Pins made of electricity conducting material (a) mechanically support the middle and top PCBs above the bottom PCB, (b) conduct electrical power from the bottom PCB to the middle and top PCBs, and (c) conduct signals from the sensor chip on the middle PCB to the bottom PCB.

In embodiments of the video camera head of the invention comprised of two PCBs electronic components for receiving signals from a solid state sensor and outputting a video signal are mounted on the bottom PCB, a solid state sensor chip is mounted on the top side of the bottom PCB, and an objective optical system and illumination means are mounted on the top PCB. Pins made of electricity conducting material mechanically

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support the top PCB above the bottom PCB and conduct electrical power from the bottom PCB to top PCB. Through vias are provided to conduct electrical power from the bottom side to the top side of the bottom PCB and to conduct signals from the sensor chip on the top side to the bottom side of the bottom PCB.

In embodiments of the video camera head of the invention comprised of four PCBs, electronic components for receiving signals from a solid state sensor and outputting a video signal are mounted on the first (bottom) and second PCBs, a solid state sensor chip is mounted on the third PCB, and an objective optical system and illumination means are mounted on the fourth (top) PCB. Pins made of electricity conducting material (a) mechanically support the second, third, and fourth PCBs above the first PCB, (b) conduct electrical power from the first PCB to the second, third, and fourth PCBs, and (c) conduct signals from the sensor chip on the third PCB to the first PCB.

In a second aspect the invention is a video camera head comprised of at least two rigid printed circuit boards (PCBS) arranged in parallel planes. In the camera head of this aspect an objective optical system and illumination means are mounted on the distal end of a housing of the camera head, a solid state sensor chip is mounted on a PCB below the objective optical system, electronic components for receiving signals from a solid state sensor and outputting a video signal are mounted on at least one of the PCBs, the at least two PCBs are mechanically supported one above the other by electrically conducting pins, and the illumination means supported on the distal end of the camera housing are output couplers of optical fibers or the distal end of light guides.

The light source for the illumination means of the video camera of the second aspect of the invention can be any conventional light source used with endoscopic systems. In these embodiments the light from the LEDs is transferred to the distal end of a housing of the camera head through hollow light guides.

In embodiments of the video camera of the second aspect of the invention the light source is LEDs that are mounted on one of the PCBs in the camera head or proximally from it. The LEDs can be mounted on a PCB together with the solid state sensor chip.

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In other embodiments the LEDs are mounted on a PCB below the PCB on which the solid state sensor chip is mounted.

In embodiments of the video camera of the second aspect of the invention the light source is located remotely from the camera head and the light is transferred directly from the light source to an output coupler on the distal end of the camera housing or to one of the PCBs where it is coupled into a hollow light guide.

In embodiments of the video camera head of the invention the pins can be either rigid or flexible.

In embodiments of the video camera head of the invention the PCBs are not circular and can have any shape, symmetric or non-symmetric.

In embodiments of the video camera head of the invention some or all of the PCBs in a camera head can be different from the shapes and dimensions of other PCBs in the camera head.

In embodiments of the video camera head of the invention some or all of the components of the objective optical system can be mounted on a housing of the camera head.

All the above and other characteristics and advantages of the invention will be further understood through the following illustrative and non-limitative description of embodiments thereof, with reference to the appended drawing.

Brief Description of the Drawing

- Fig. 1 schematically shows the structure of one embodiment of the camera head of the invention; and
- Fig. 2 and Fig. 3 schematically show a second embodiment of the camera head of the invention.

Detailed Description of Embodiments of the Invention

Fig. 1 schematically shows the structure of an embodiment of the camera head (10) of the invention. This embodiment of the camera head of the present invention comprises three rigid PCBs (12a, 12b, and 12c). The three PCBs are arranged in three parallel planes one above the other. (Note that for convenience the camera head is described as if it were oriented with its central axis vertical. This defines the relative directions such as top and bottom used herein.)

The middle PCB (12b) is mechanically supported above the lower PCB (12c) by six short pins (14) and the upper PCB (12a) is mechanically supported above the lower PCB (12c) by two longer pins (16) that pass through vias in PCB (12b). It is noted that embodiments of the camera head (10) may comprise more or less than 6 pins (14) and more than two pins (16).

Metallization (18) is created on the surface of the lower PCB (12c) and electronic components (20) for receiving signals from a solid state image sensor, e.g. CMOS, and outputting a video signal are electrically connected to this metallization. A camera cable (30) that conducts power to the camera head and video signals from it to a remote signal processor is connected by means of through vias to the metallization pattern on the top side of PCB (12c).

Middle PCB (12b) supports the solid state sensor chip (22).

The upper PCB (12a) supports the objective optical system (24) inside its housing (26) and illumination means, e.g. at least one LED or a ring array of LEDs (28) surrounding housing (26).

Pins (14) and (16) are made of electricity conducting material. Therefore they serve the dual purpose of mechanically supporting the upper two PCBs and also of conducting power to and signals from the sensor chip (22) and power to LEDs 28.

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The internal structure of camera head (10) thus addresses all four of the obstacles discussed in the background section of this application. Firstly use of rigid PCBs instead of flexible PCBs eliminates the bending radius of the flexible PCB that usually increases the diameter of the camera head. Secondly the use of the electrically connecting pins allows for transferring adequate amounts of current for the illumination sources. Thirdly and fourthly the use of the electrically connecting pins eliminates most of the difficulty of making the internal wiring connections and therefore greatly simplifies the assembly process, thereby making camera head (10) into a device that is very suitable for mass production manufacturing.

It is noted that an embodiment of the camera head of the invention can comprise two PCBs in which case the electronic components are located on the bottom surface of the lower PCB and the sensor chip on the top surface of the bottom PCB and the objective lens system and illumination source on the upper PCB. Other embodiments can comprise more than three PCBs, for example four in which the lower two PCBs support electronic components, the third PCB supports the sensor chip and the top PCB supports the objective optical system and illumination means. In all embodiments electricity conducting pins serve the dual purposes of separating and mechanically supporting the PCBs and of conducting electric power and video signals between them.

In other embodiments of the invention the illumination means supported on the uppermost PCB are output couplers of optical fibers or light guides. In these embodiments the light source can be any conventional light source used with endoscopic systems, e.g. LEDs that can be mounted on one of the lower PCBs in the camera head or proximally from it. In some embodiments the electrically conducting pins may be combined with hollow light guides.

In one embodiment, shown schematically in Fig. 2, the camera head comprises three PCBs that are mechanically supported one above the other by electricity conducting pins 14,16. The two lower PCBs 12b,12c support electronic components (not shown in the figure) for receiving signals from a solid state image sensor 22 and outputting a video signal. The uppermost PCB 12a supports the solid state sensor 22 and one or

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more LEDs 28, e.g. a circular array, which surround the sensor. In this embodiment an objective lens system 24 enclosed in its housing 26 is held in place above the sensor 22 by a support structure, e.g. a hollow tube attached at its bottom end to the PCB 12a or by a structure attached to a camera housing 34 that surrounds the internal components of the camera head. The camera head also comprises vertical tubular light guides 32, which transfer light from the LEDs 28 to the height of the objective lens 24 on the distal end 36 of the camera housing 34 facing the object to be imaged. The light guides 32 are supported above the LEDs 28, for example by being attached at their bottom ends to the PCB 12a or by supports attached to the interior of the camera housing 34.

The electronic components located on PCBs 12a and 12b can be redistributed onto one PCB only and/or some can be located on PCB 12a thereby allowing this embodiment of the camera head to comprise only two PCBs. In all embodiments camera cable 30 is connected to electronic components on the bottom PCB.

A variation of the embodiment shown in Fig. 2 is shown schematically in Fig. 3. In the camera head shown in Fig. 3, electronic components (not shown) are located on PCBs 12a and 12c (and in some versions also on 12b), the LEDs 28 are on PCB 12c and light guides 32 transfer light from the LEDs 28 to the height of the objective lens 24 the distal end 36 of the camera housing 34 facing the object to be imaged.

In other embodiments the light source can be located remotely from the camera head and the light transferred directly from the light source to an output coupler on the distal end 36 of the camera housing 34 or alternately to one of the PCBs where it is coupled into a hollow light guide as shown in Figs. 2 and 3.

Although embodiments of the invention have been described by way of illustration, it will be understood that the invention may be carried out with many variations, modifications, and adaptations, without exceeding the scope of the claims, for example:

- a) the pins may be rigid or flexible;
- b) the shape of the PCBs is not circular but can be any shape symmetric, e.g. square or rectangular, or asymmetric;

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- c) the shapes and dimensions of some or all of the PCBs in a camera head can be different from the shapes and dimensions of other PCBs in the camera head; and
- d) in embodiments of the camera head, some or all of the components of an objective optical system can be mounted on the housing of the camera head.

Claims

1. A video camera head comprised of at least two rigid printed circuit boards (PCBS) arranged in parallel planes, wherein the at least two PCBs are mechanically supported one above the other by pins made of an electricity conducting material that conduct electrical power from the bottom PCB to electronic components or illumination means mounted on the other PCBs of the at least two PCBs and signals from a solid state sensor chip mounted on one of the other PCBs of the at least two PCBs to the bottom PCB.
2. The video camera head of claim 1 wherein the illumination means comprise at least one LED.
3. The video camera head of claim 2 wherein the illumination means comprise a ring array of LEDs.
4. The video camera head of claim 1 comprising an objective optical system.
5. The video camera head of claim 1 comprised of three PCBs, wherein electronic components for receiving signals from a solid state sensor and outputting a video signal are mounted on the bottom PCB, a solid state sensor chip is mounted on the middle PCB, an objective optical system and illumination means are mounted on the top PCB, and pins made of electricity conducting material (a) mechanically support the middle and top PCBs above the bottom PCB, (b) conduct electrical power from the bottom PCB to the middle and top PCBs, and (c) conduct signals from the sensor chip on the middle PCB to the bottom PCB.
6. The video camera head of claim 1 comprised of two PCBs, wherein electronic components for receiving signals from a solid state sensor and outputting a video signal are mounted on the bottom PCB, a solid state sensor chip is mounted on the top side of the bottom PCB, an objective optical system and illumination means are mounted on the top PCB, and pins made of electricity conducting material mechanically support the top PCB above the bottom PCB and conduct electrical power from the bottom PCB to top PCB, and through vias are used to conduct

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electrical power from the bottom side to the top side of the bottom PCB and to conduct signals from the sensor chip on the top side to the bottom side of the bottom PCB.

7. The video camera head of claim 1 comprised of four PCBs, wherein electronic components for receiving signals from a solid state sensor and outputting a video signal are mounted on the first (bottom) and second PCBs, a solid state sensor chip is mounted on the third PCB, an objective optical system and illumination means are mounted on the fourth (top) PCB, and pins made of electricity conducting material (a) mechanically support the second, third, and fourth PCBs above the first PCB, (b) conduct electrical power from the first PCB to the second, third, and fourth PCBs, and (c) conduct signals from the sensor chip on the third PCB to the first PCB.
8. A video camera head comprised of at least two rigid printed circuit boards (PCBS) arranged in parallel planes, wherein an objective optical system and illumination means are mounted on the distal end of a housing of the camera head, a solid state sensor chip is mounted on a PCB below the objective optical system, electronic components for receiving signals from a solid state sensor and outputting a video signal are mounted on at least one of the PCBs, the at least two PCBs are mechanically supported one above the other by electrically conducting pins, and the illumination means supported on the distal end of the camera housing are output couplers of optical fibers or the distal end of light guides.
9. The video camera of claim 8 wherein a light source for the illumination means is any conventional light source used with endoscopic systems.
10. The video camera of claim 9 wherein the light source is at least one LED that is mounted on one of the PCBs in the camera head or proximally from it.
11. The video camera of claim 10 wherein the light from the at least one LED is transferred to the distal end of a housing of the camera head through hollow light guides.

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12. The video camera of claim 10 wherein the at least one LED is mounted on a PCB together with the solid state sensor chip.
13. The video camera of claim 10 wherein the at least one LED is mounted on a PCB below the PCB on which the solid state sensor chip is mounted.
14. The video camera of claim 9 wherein the light source is located remotely from the camera head and the light is transferred directly from the light source to an output coupler on the distal end of the camera housing or to one of the PCBs where it is coupled into a hollow light guide.
15. The video camera of claim 1 wherein the pins are one of rigid or flexible.
16. The video camera of claim 1 wherein the PCBs are of any shape, symmetric or non-symmetric.
17. The video camera of claim 1 wherein the shapes and dimensions of some or all of the PCBs in a camera head are different from the shapes and dimensions of other PCBs in the camera head.
18. The video camera of claim 8 wherein some or all of the components of the objective optical system are mounted on the housing of the camera head.

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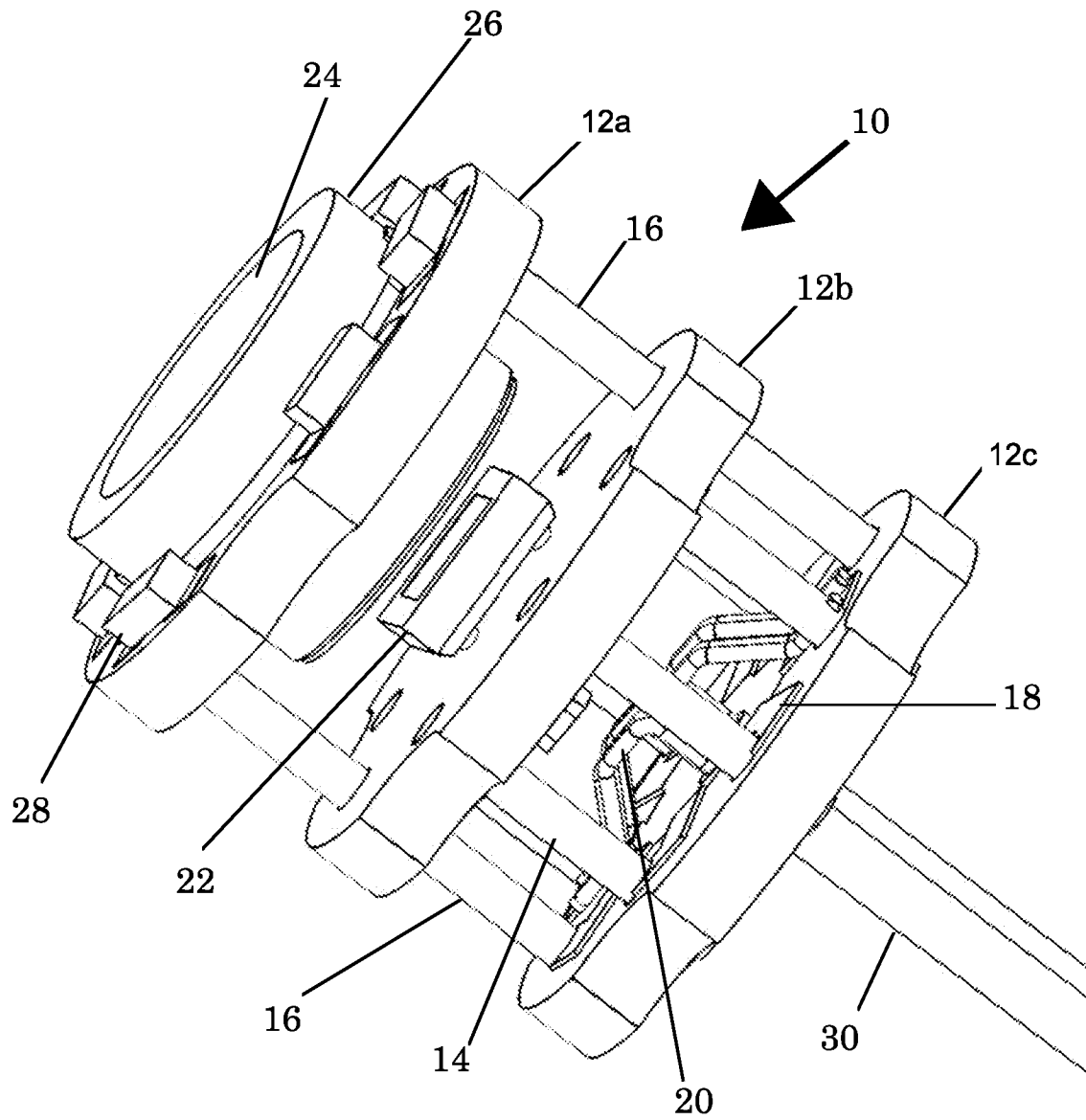


Fig. 1

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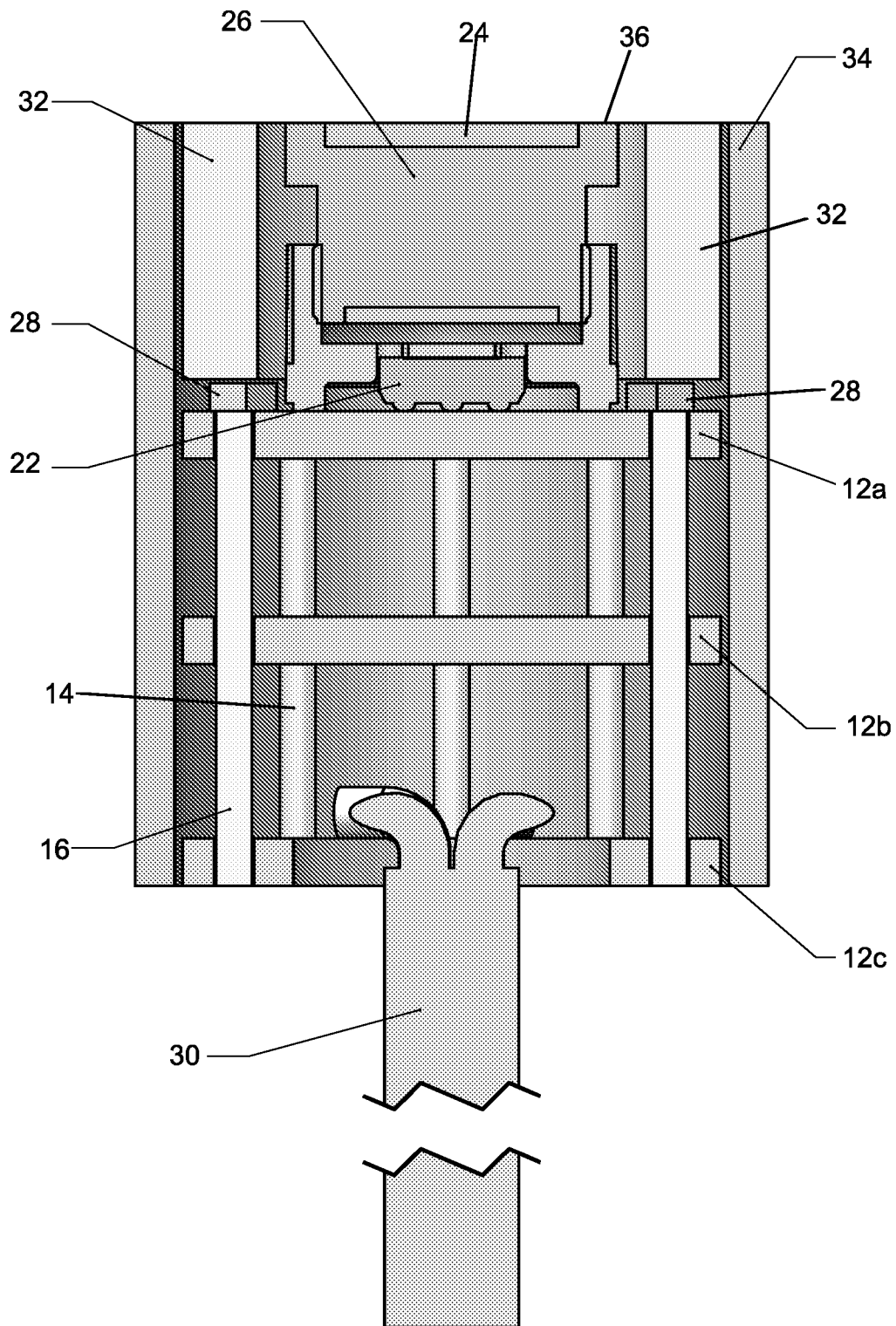


Fig. 2

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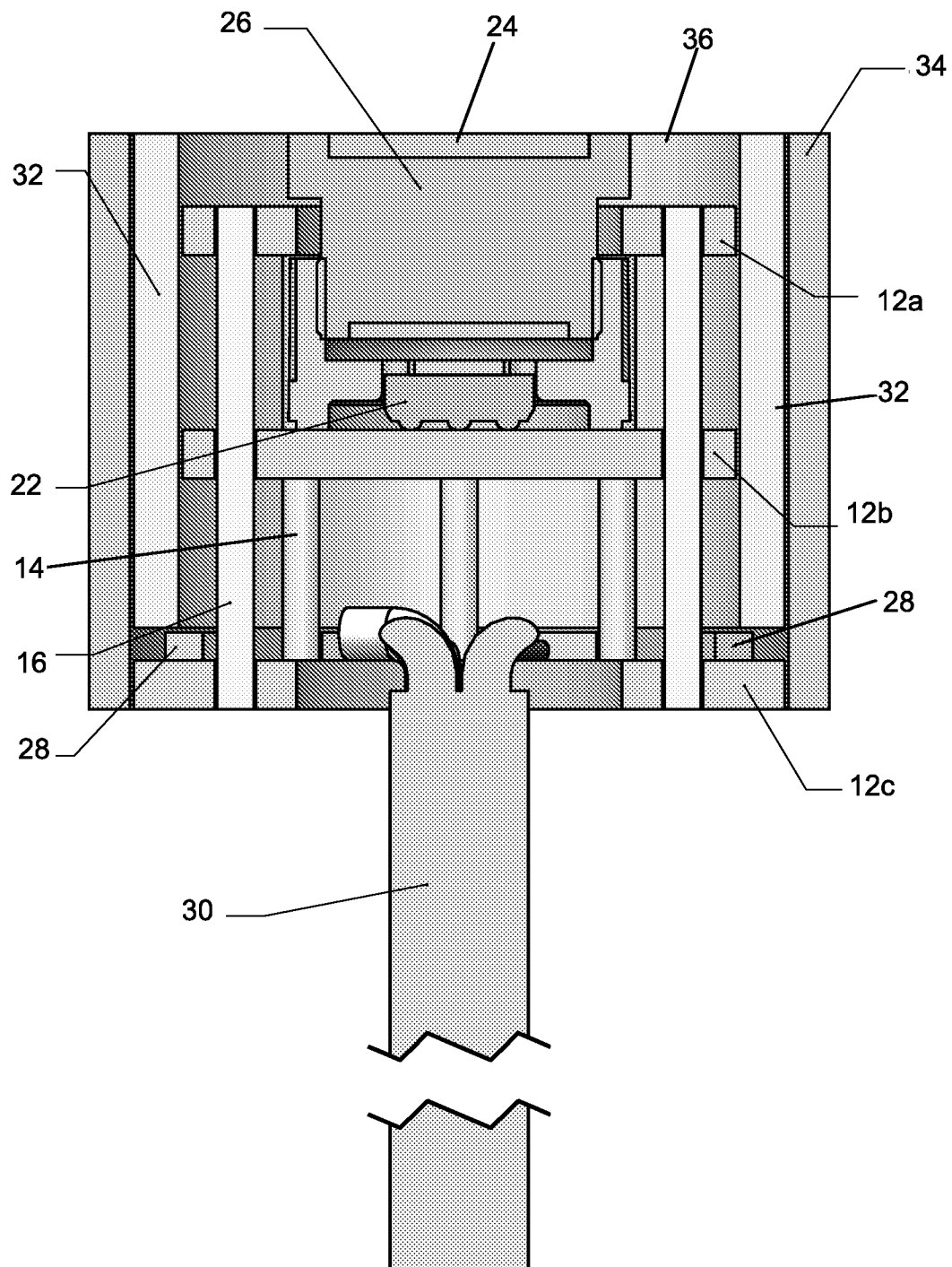


Fig.3

INTERNATIONAL SEARCH REPORT

International application No.

PCT/IL2016/050603

A. CLASSIFICATION OF SUBJECT MATTER IPC (2016.01) H05K 1/14, H04N 5/225 According to International Patent Classification (IPC) or to both national classification and IPC		
B. FIELDS SEARCHED Minimum documentation searched (classification system followed by classification symbols) IPC (2016.01) H05K 1/14, H04N 5/225 Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched Electronic data base consulted during the international search (name of data base and, where practicable, search terms used) Databases consulted: THOMSON INNOVATION, Esp@cenet, Google Patents, FamPat database Search terms used: camera, PCB, parallel, illumination, sensor, H05K2201/042		
C. DOCUMENTS CONSIDERED TO BE RELEVANT		
Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2010185052 A1 Chang 22 Jul 2010 (2010/07/22) entire document	1-18
X	US 2004171914 A1 Avni 02 Sep 2004 (2004/09/02) entire document	1
<input type="checkbox"/> Further documents are listed in the continuation of Box C. <input checked="" type="checkbox"/> See patent family annex.		
* Special categories of cited documents: "A" document defining the general state of the art which is not considered to be of particular relevance "E" earlier application or patent but published on or after the international filing date "L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified) "O" document referring to an oral disclosure, use, exhibition or other means "P" document published prior to the international filing date but later than the priority date claimed "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention "X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art "&" document member of the same patent family		
Date of the actual completion of the international search 19 Sep 2016		Date of mailing of the international search report 25 Sep 2016
Name and mailing address of the ISA: Israel Patent Office Technology Park, Bldg.5, Malcha, Jerusalem, 9695101, Israel Facsimile No. 972-2-5651616		Authorized officer ROASH Yoaela Telephone No. 972-2-5657807

INTERNATIONAL SEARCH REPORT
Information on patent family members

International application No.
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Patent document cited search report	Publication date	Patent family member(s)	Publication Date
US 2010185052 A1	22 Jul 2010	US 2010185052 A1	22 Jul 2010
		EP 2208456 A1	21 Jul 2010
		TW 201028125 A	01 Aug 2010
		TW I423781 B	21 Jan 2014
<hr/>			
US 2004171914 A1	02 Sep 2004	US 2004171914 A1	02 Sep 2004
		US 7998065 B2	16 Aug 2011
		AT 404114 T	15 Aug 2008
		AT 546086 T	15 Mar 2012
		AU 2002311613 A1	02 Jan 2003
		DE 60228266 D1	25 Sep 2008
		EP 1418833 A2	19 May 2004
		EP 1418833 A4	13 Apr 2005
		EP 1418833 B1	13 Aug 2008
		EP 1982636 A1	22 Oct 2008
		EP 1982636 B1	22 Feb 2012
		EP 1982636 B2	07 Sep 2016
		IL 159450 A	22 Sep 2009
		IL 159450 D0	01 Jun 2004
		JP 2004533879 A	11 Nov 2004
		JP 4256256 B2	22 Apr 2009
		JP 2006297119 A	02 Nov 2006
		JP 4751772 B2	17 Aug 2011
		WO 02102224 A2	27 Dec 2002
		WO 02102224 A3	11 Mar 2004
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